

# CMP1608A/CMB1608A/CMI1608A/CMF1608A

80V, 2.8mΩ typ., 180A N-Channel MOSFET

## General Description

This N-Channel MOSFET is produced by using Cmos's advanced trench technology process that has been tailored to minimize the on-state resistance while maintaining superior switching performance.

## Product Summary

BVDSS	R <sub>D(on)</sub> max.	ID
80V	3.1mΩ	180A

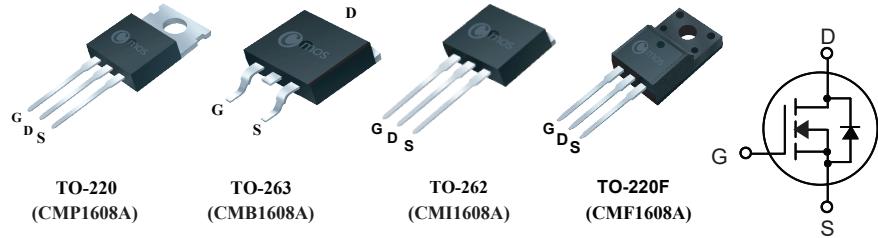
## Applications

- Battery management
- Uninterruptible Power Supply

## TO-220/263/262/220F Pin Configuration

## Features

- Low On-Resistance
- 100% avalanche tested
- RoHS Compliant



## Absolute Maximum Ratings

Symbol	Parameter	220/263/262	220F	Units
V <sub>DS</sub>	Drain-Source Voltage	80		V
V <sub>GS</sub>	Gate-Source Voltage	±20		V
I <sub>D</sub> @T <sub>C</sub> =25°C	Continuous Drain Current	180	180*	A
I <sub>D</sub> @T <sub>C</sub> =100°C	Continuous Drain Current	126	126*	A
I <sub>DM</sub>	Pulsed Drain Current	720	720*	A
EAS	Single Pulse Avalanche Energy (Note 1)	2415		mJ
P <sub>D</sub> @T <sub>C</sub> =25°C	Total Power Dissipation	300	45	W
T <sub>STG</sub>	Storage Temperature Range	-55 to 150		°C
T <sub>J</sub>	Operating Junction Temperature Range	-55 to 150		°C

\* Drain current limited by maximum junction temperature.

## Thermal Data

Symbol	Parameter	220/263/262	220F	Unit
R <sub>θJA</sub>	Thermal Resistance Junction-ambient Max.(min. footprint)	84	84	°C/W
R <sub>θJC</sub>	Thermal Resistance Junction-case Max.	0.42	2.78	°C/W

**Electrical Characteristics (T<sub>J</sub>=25°C , unless otherwise noted)**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V , I <sub>D</sub> =250μA	80	---	---	V
R <sub>DS(ON)</sub>	Static Drain-Source On-Resistance	V <sub>GS</sub> =10V , I <sub>D</sub> =80A	---	2.8	3.1	mΩ
V <sub>GSS(th)</sub>	Gate Threshold Voltage	V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =250μA	2	---	4	V
I <sub>DSS</sub>	Drain-Source Leakage Current	V <sub>DS</sub> =80V , V <sub>GS</sub> =0V	---	---	1	uA
I <sub>GSS</sub>	Gate-Source Leakage Current	V <sub>GS</sub> = ±20V , V <sub>DS</sub> =0V	---	---	±100	nA
g <sub>fs</sub>	Forward Transconductance	V <sub>DS</sub> =10V , I <sub>D</sub> =20A	---	46	---	S
R <sub>g</sub>	Gate Resistance	V <sub>DS</sub> =0V , V <sub>GS</sub> =0V , f=1MHz	---	1.3	---	Ω
Q <sub>g</sub>	Total Gate Charge	V <sub>DD</sub> =40V , I <sub>D</sub> =50A	---	172	---	nC
Q <sub>gs</sub>	Gate-Source Charge	V <sub>GS</sub> =10V	---	39	---	
Q <sub>gd</sub>	Gate-Drain Charge		---	68	---	
T <sub>d(on)</sub>	Turn-On Delay Time		---	30	---	ns
T <sub>r</sub>	Rise Time	V <sub>DS</sub> =40V	---	113	---	
T <sub>d(off)</sub>	Turn-Off Delay Time	R <sub>G_ext</sub> =2.7Ω , V <sub>GS</sub> =10V	---	81	---	
T <sub>f</sub>	Fall Time		---	116	---	
C <sub>iss</sub>	Input Capacitance		---	8050	---	pF
C <sub>oss</sub>	Output Capacitance	V <sub>DS</sub> =25V , V <sub>GS</sub> =0V , f=1MHz	---	1050	---	
C <sub>rss</sub>	Reverse Transfer Capacitance		---	800	---	

**Diode Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I <sub>S</sub>	Diode continuous forward current	V <sub>G</sub> =V <sub>D</sub> =0V , Force Current	---	---	180	A
I <sub>S,pulse</sub>	Diode pulse current		---	---	720	A
V <sub>SD</sub>	Diode Forward Voltage	V <sub>GS</sub> =0V , I <sub>F</sub> =30A , T <sub>J</sub> =25 °C	---	0.76	1.4	V

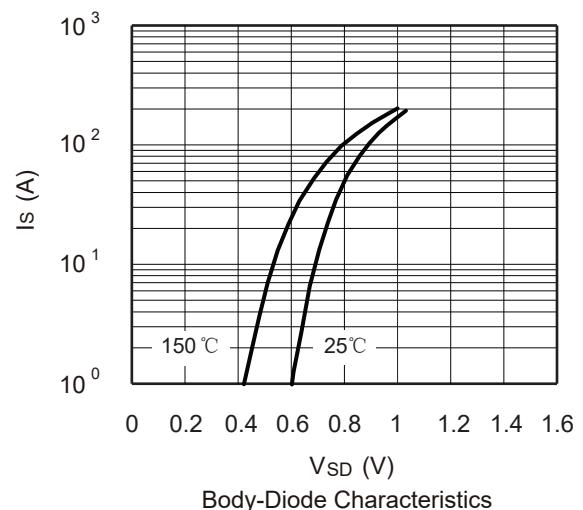
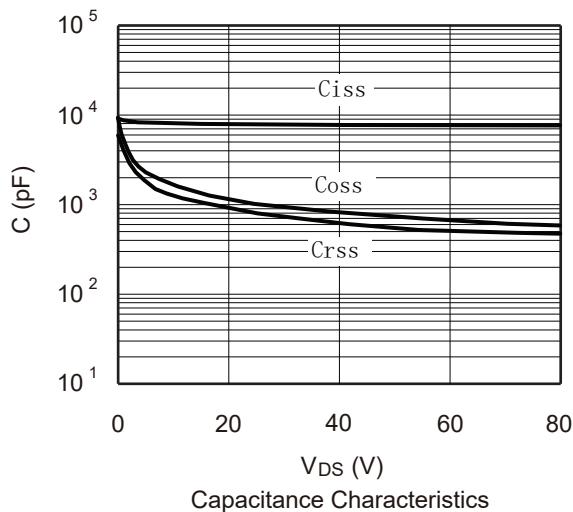
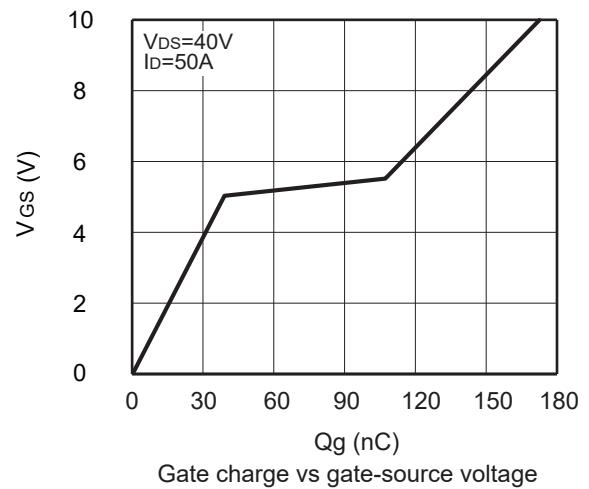
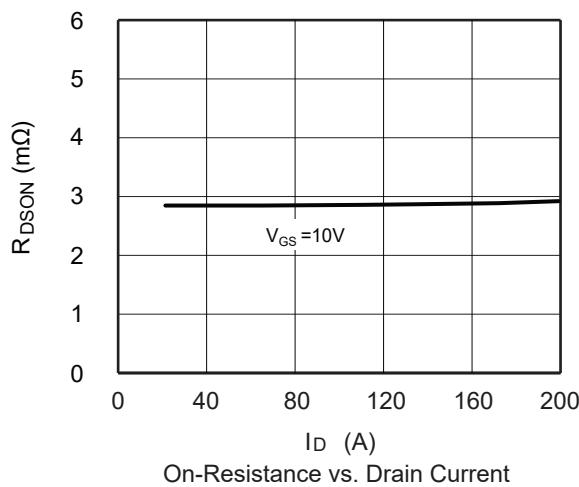
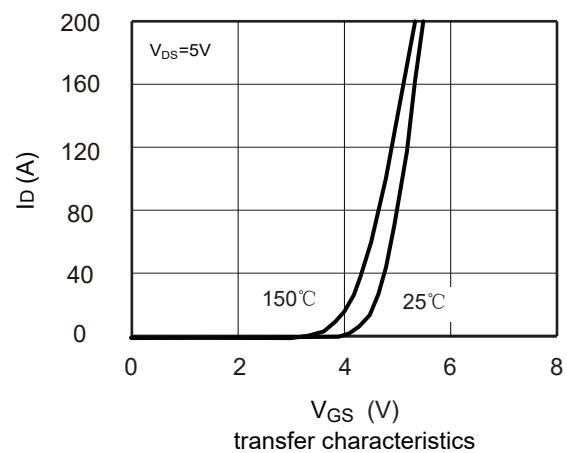
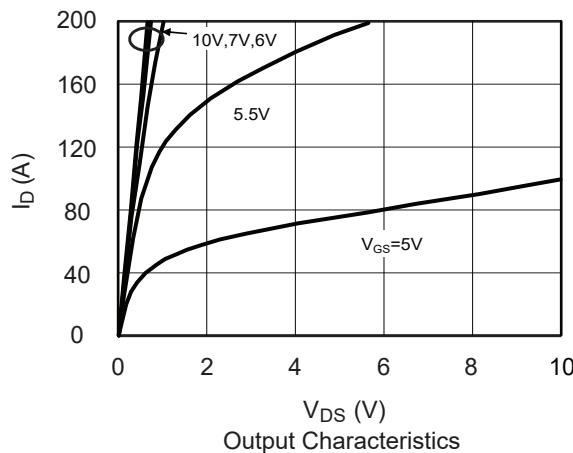
Note :

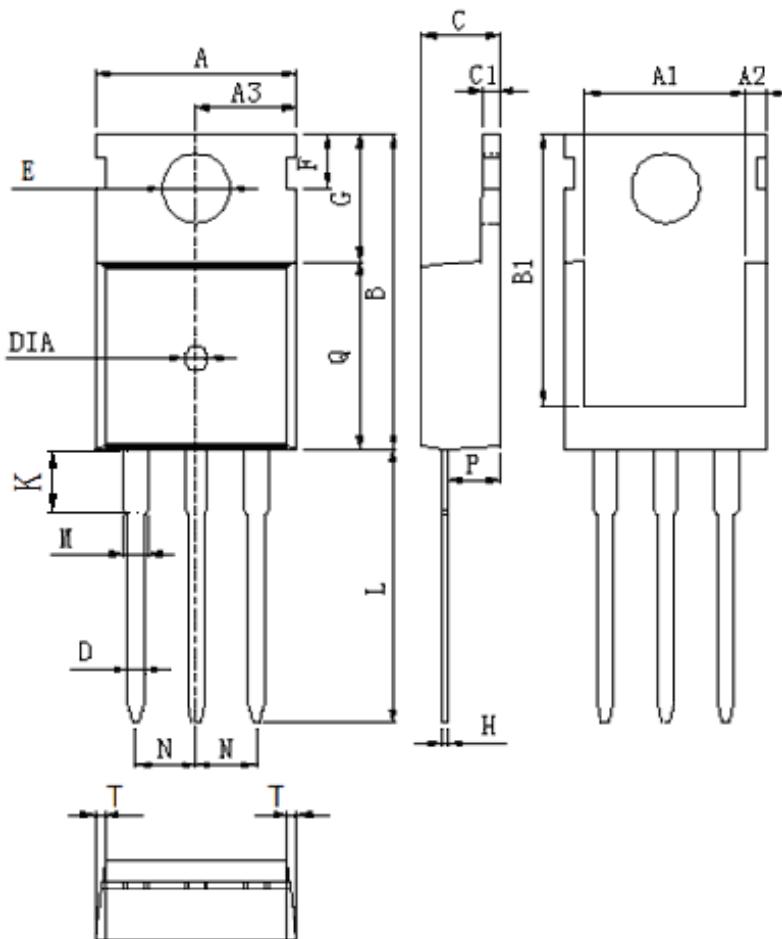
1.The EAS data shows Max. rating .The test condition is V<sub>DS</sub>=50V , V<sub>GS</sub>=10V , L=1mH , I<sub>AS</sub>=69.5A.

This product has been designed and qualified for the consumer market.

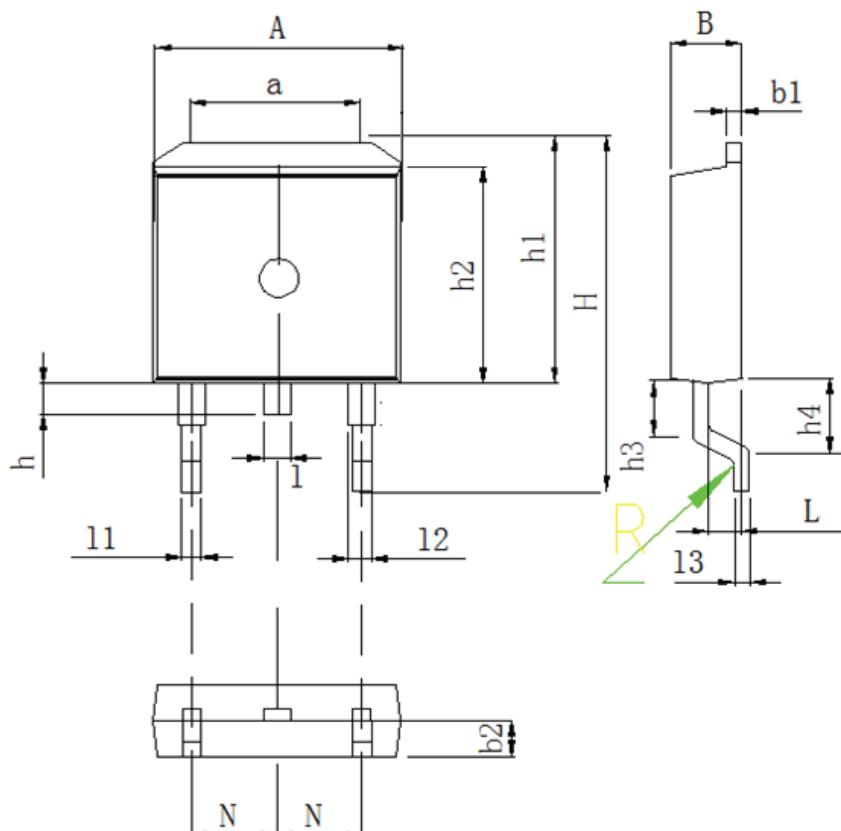
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Cmos reserves the right to improve product design ,functions and reliability without notice.Please refer to the latest version of specification.

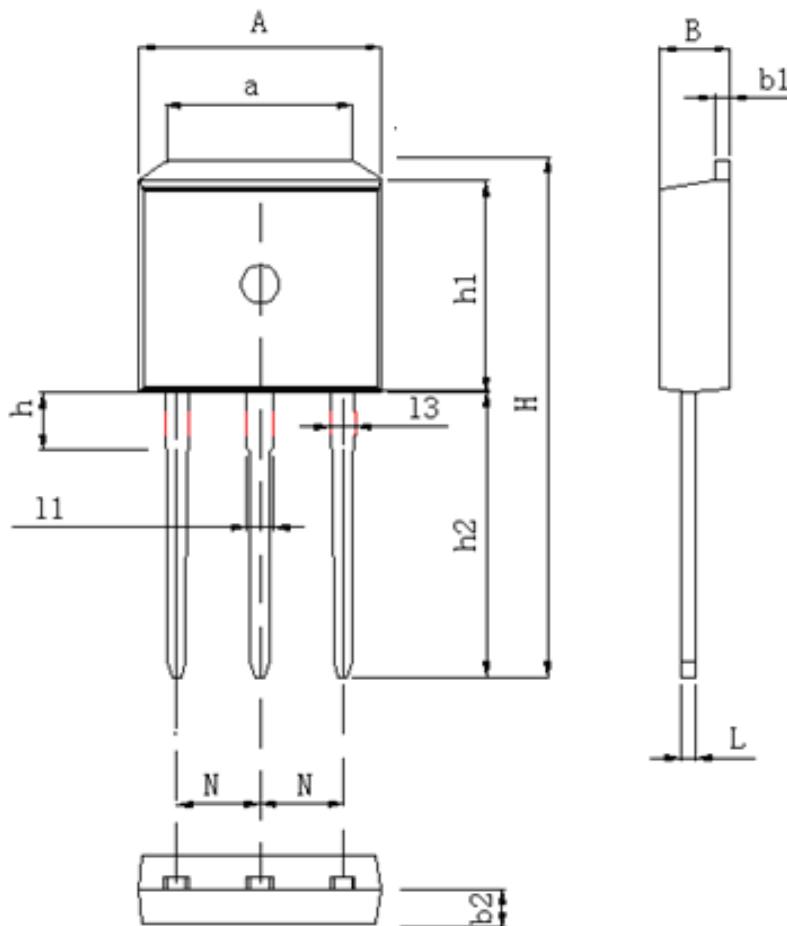
**Typical Characteristics**


**Package Dimension**
**TO-220**
**Unit :mm**


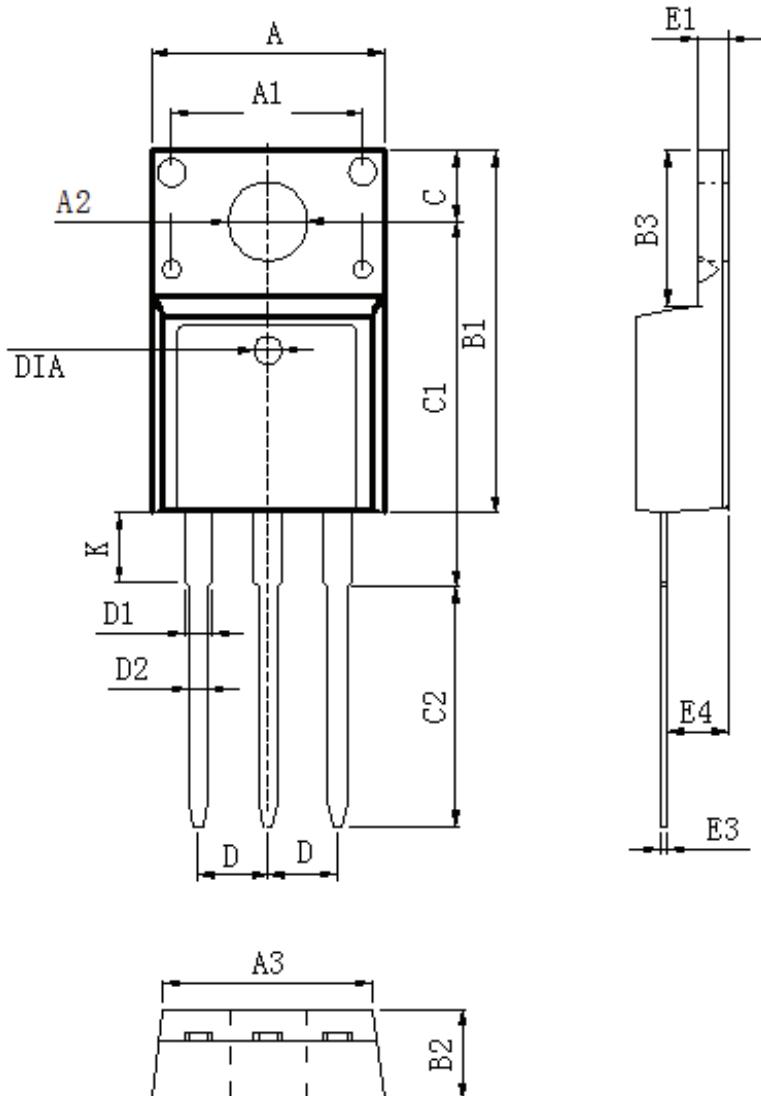
DIM	MILLIMETERS
A	$10.0 \pm 0.3$
A1	$8.64 \pm 0.2$
A2	$1.15 \pm 0.1$
A3	$5.0 \pm 0.2$
B	$15.8 \pm 0.4$
B1	$13.2 \pm 0.3$
C	$4.56 \pm 0.1$
C1	$1.3 \pm 0.2$
D	$0.8 \pm 0.2$
E	$3.6 \pm 0.2$
F	$2.95 \pm 0.3$
G	$6.5 \pm 0.3$
H	$0.5 \pm 0.1$
K	$3.1 \pm 0.2$
L	$13.2 \pm 0.4$
M	$1.25 \pm 0.1$
N	$2.54 \pm 0.1$
P	$2.4 \pm 0.3$
Q	$9.0 \pm 0.3$
T	W:0.35
DIA	◎1.5(deep 0.2)

**Package Dimension**
**TO-263**
**Unit :mm**


DIM	MILLIMETERS
A	9.8±0.2
a	7.4±0.4
B	4.5±0.2
b1	1.3±0.05
b2	2.4±0.2
H	15.5±0.3
h	1.54±0.2
h1	10.5±0.2
h2	9.2±0.1
h3	1.54±0.2
h4	2.7±0.2
L	2.4±0.2
1	1.3±0.1
11	0.8±0.1
12	1.3±0.1
13	0.5±0.1
N	2.54±0.1
R	0.5R±0.05

**Package Dimension**
**TO-262**
**Unit :mm**


DIM	MILLIMETERS
A	9.98 ± 0.2
a	7.4 ± 0.4
B	4.5 ± 0.2
b1	1.3 ± 0.05
b2	2.4 ± 0.2
H	23.9 ± 0.3
h	3.1 ± 0.2
h1	9.16 ± 0.2
h2	13.2 ± 0.2
L	0.5 ± 0.1
l1	1.3 ± 0.1
l2	0.8 ± 0.1
N	2.45 ± 0.1

**Package Dimension**
**TO-220F**
**Unit :mm**


DIM	MILLIMETERS
A	$10.16 \pm 0.3$
A1	$7.00 \pm 0.1$
A2	$3.3 \pm 0.2$
A3	$9.5 \pm 0.2$
B1	$15.87 \pm 0.3$
B2	$4.7 \pm 0.2$
B3	$6.68 \pm 0.4$
C	$3.3 \pm 0.2$
C1	$12.57 \pm 0.3$
C2	$10.02 \pm 0.5$
D	$2.54 \pm 0.05$
D1	$1.28 \pm 0.2$
D2	$0.8 \pm 0.1$
K	$3.1 \pm 0.3$
E1	$2.54 \pm 0.1$
E3	$0.5 \pm 0.1$
E4	$2.76 \pm 0.2$
DIA	◎1.5 (deep 0.2)

